



Material Content Data Sheet



Sales Product Name		TLE9843-2QX		Issued		24. January 2018			
MA#		MA001472568							
Package		PG-VQFN-48-31		Weight*		129.64 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.417	2.64	2.64	26360	26360	
leadframe	inorganic material	phosphorus	7723-14-0	0.018	0.01		138		
		non noble metal	zinc	7440-66-6	0.072	0.06		553	
		non noble metal	iron	7439-89-6	1.433	1.11		11055	
wire	non noble metal	non noble metal	copper	7440-50-8	58.193	44.89	46.07	448880	460626
		non noble metal	copper	7440-50-8	0.599	0.46	0.46	4622	4622
		encapsulation	organic material	carbon black	1333-86-4	0.185	0.14		1429
plastics	plastics	epoxy resin	-	7.840	6.05		60477		
		inorganic material	silicondioxide	60676-86-0	53.708	41.43	47.62	414288	476194
		leadfinish	non noble metal	tin	7440-31-5	2.596	2.00	2.00	20028
plating	noble metal	silver	7440-22-4	0.614	0.47	0.47	4735	4735	
glue	plastics	epoxy resin	-	0.222	0.17		1710		
		noble metal	silver	7440-22-4	0.742	0.57	0.74	5725	7435
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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